



at least a part of the unsaturated compound (A) is an unsaturated compound having the fluorene skeleton represented by the formula (3) in its structural unit.

3. A photo- or heat-curable resin composition as described in claim 1 wherein at least one kind of other unsaturated compound (E) selected from other monomers and oligomers is incorporated at a rate of 100 parts or less per 100 parts by weight of the component A in addition to the components A, B, C and D.

4. A printed wiring board wherein a resin insulation layer is formed by the cured product of a photo- or heat-curable resin composition as described in claim 1.

5. A cured resin formed by curing a photo- or heat-curable resin composition as described in claim 1.